

# Alloy MC-AMI355/325

## High Performance GPU Cold Plate

Alloy's MC-AMI355/325 cold plate delivers industry-leading thermal performance with embedded microcapillary™ channels, enabled by Alloy's patented Stack Forging™ process. Designed for the MC-AMI355/325, it ensures efficient heat removal at extreme power densities.



### Key Benefits

- **Low thermal resistance:** Alloy's complex microcapillaries allow for more efficient and even cooling across the entire chip
- **Ultra-low pressure drop:** Alloy's unique parallelization enables better thermal performance without sacrificing pressure drop
- **Leak-tight reliability:** single-piece construction eliminates brazing and seals
- **Targeted cooling where needed:** localized flow paths direct cooling to hot spots
- **Stiff and strong:** no leakage or permanent deflection at pressure drop up to 2,000 psi and above

### MC-AMI355/325 Cold Plate Specifications

|                        |                                                                   |
|------------------------|-------------------------------------------------------------------|
| Product Name           | Alloy MC-AMI355/325                                               |
| Compatibility          | AMD MI355/325                                                     |
| Cooling Technology     | Single-phase DLC coldplate, embedded microcapillary flow channels |
| Thermal Resistance*    | <0.125 C/W @ 2 LPM (PG25)                                         |
| Pressure Drop*         | <6 psi @ 2 LPM (PG25)                                             |
| Dimensions (L x W x H) | 177.5mm x 101mm x 38.9mm                                          |
| Weight*                | 1363 grams                                                        |
| Coolant                | PGW25 @ 20°C inlet temperature                                    |
| Material               | Copper                                                            |

\*for Cu 110

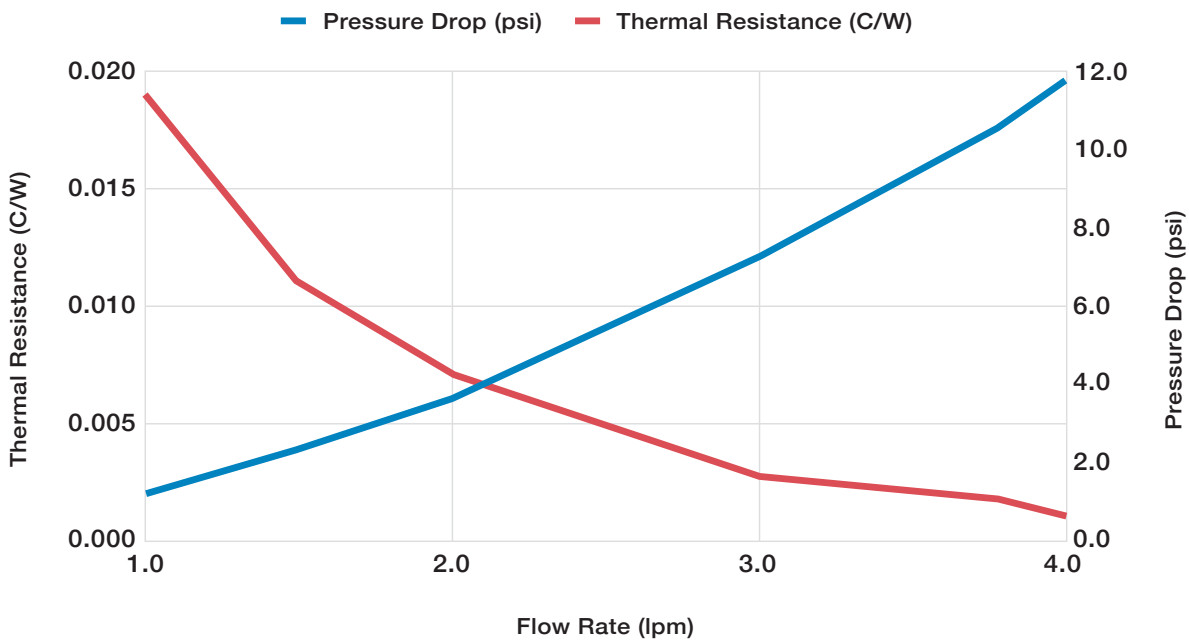
### US Manufacturing

Alloy's portfolio also includes peripheral and memory cold plates for DIMMs, interconnect cards, and other components, **delivering 100% liquid cooling coverage across the entire system.**

## Features

- Ultra-thin microchannels maximize heat transfer efficiency
- 3D engineered geometries expand surface area for enhanced capacity
- Massively parallelized networks with short flow paths minimize flow resistance
- Copper 110 or Aluminum 6061 single-piece construction

### Alloy MI355/325 Cold Plate Performance



Note: Thermal resistance does not include TIM. Data collected with a chassis resistor TTV at 500 W. Performance for Cu 110.

Learn more and see how we can help solve  
your toughest thermal challenges.

Reach out to [info@alloyenterprises.co](mailto:info@alloyenterprises.co)

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